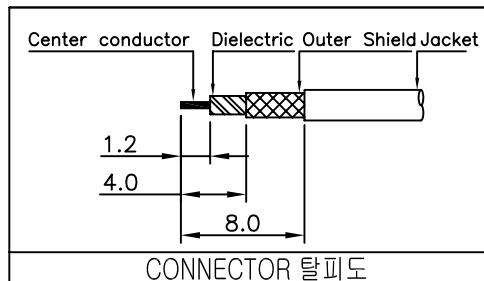
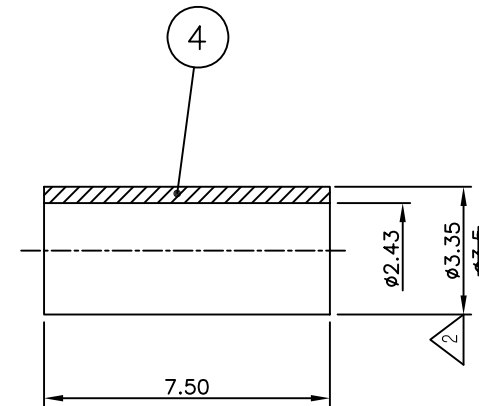
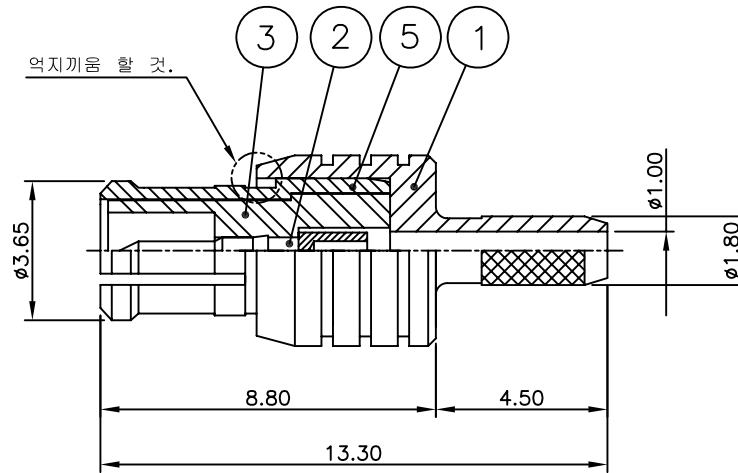


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration			1996.04.26.
1	커넥터 압착부 바디 부러짐 현상 방지로 인한 R추가	S.Y.EUN	S.H.KIM	2021.12.24.
2	[설번No.202201-0009] PIPE 압착 후 BURR 발생 개선으로 인한 PIPE 변경	S.Y.EUN	S.H.KIM	2022.01.10.



5	JACK	1	BeCu C17300	Gold Plate	DJA00009-5/1
4	FERRULE	1	MBsBD C3604BD-F	Nickel Plate Gold Plate	DFE00018-5/3 DFE00008-5/1
3	INSULATOR	1	TEFLON	White	DIN00066-N/1
2	CONTACT	1	MBsBD C3604BD-F	Gold Plate	DCT00063-5/1
1	BODY	1	MBsBD C3604BD-F	Gold Plate	DBD00029-5/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal ± 0.1	DATE 2022. 01. 10.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle $\pm 1^\circ$	APPROVED BY	S.H.KIM	
MATERIAL	-	CHECKED BY		TITLE MCX50-PC-RG178
	-	DRAWN BY	S.Y.EUN	
FINISH	-	SCALE	5/1	 A4 DWG NO. CN00022-7/1 REVISION 2 SHEET 1 of 1
	-	UNIT	mm	